

PRODUCT NUMBER	NO. OF POS.	MATING LENGTH DIM H	OVERALL LENGTH DIM K	DIM L	NOTES
69168-X06	2 X 3	0.230/5.84	0.300/7.62	0.200/5.08	
↑ -X08	2 X 4	0.230/5.84	0.400/10.16	0.300/7.62	
-X08A	2 X 4	0.210/5.33	0.400/10.16	0.300/7.62	NOTE 6
-X10	2 X 5	0.230/5.84	0.500/12.70	0.400/10.16	
-X10A	2 X 5	0.210/5.33	0.500/12.70	0.400/10.16	NOTE 6
-X12	2 X 6	0.230/5.84	0.600/15.24	0.500/12.70	
-X14	2 X 7	0.230/5.84	0.700/17.78	0.600/15.24	
-X16	2 X 8	0.230/5.84	0.800/20.32	0.700/17.78	
-X16A	2 X 8	0.210/5.33	0.800/20.32	0.700/17.78	NOTE 6
-X18	2 X 9	0.230/5.84	0.900/22.86	0.800/20.32	
-X18A	2 X 9	0.210/5.33	0.900/22.86	0.800/20.32	NOTE 6
-X20	2 X 10	0.230/5.84	1.000/25.40	0.900/22.86	
-X22	2 X 11	0.230/5.84	1.100/27.94	1.000/25.40	
-X24	2 X 12	0.230/5.84	1.200/30.48	1.100/27.94	
-X26	2 X 13	0.230/5.84	1.300/33.02	1.200/30.48	
↓ -X28	2 X 14	0.230/5.84	1.400/35.56	1.300/33.02	
69168-X30	2 X 15	0.230/5.84	1.500/38.10	1.400/35.56	

PIN PLATING CODES

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-1YY	30u"/.76u (SEE NOTE 10) 50u"/1.27u Ni
-2YY	15u/.38u (SEE NOTE 10) 50u"/1.27u Ni
-3YY	50u"/1.27u (SEE NOTE 10) 50u"/1.27u Ni
-4YY	100u"/2.54u MIN Sn 50u"/1.27u Ni (SEE NOTE 11)
-4YYHLF	
-7YY	30u"/.76u (SEE NOTE 10) OVER 50u"/1.27u Ni
-8YY	15u"/.38u (SEE NOTE 10) OVER 50u"/1.27u Ni

NOTES:

- I. MOLDING MAT'L: GLASS REINFORCED HTN, COLOR: BLACK
FLAME RETARDANT PER UL 94 V-0
MAXIMUM OPERATING TEMPERATURE: 130° C
OR
MINERAL FILLED LCP, COLOR BLACK
FLAME RETARDANT PER UL 94 V-0

2. PIN MATERIAL: 3/4 HD PHOS. BRZ.

3. NO SLOTS ON 2 X 5 POSITION OR SMALLER PRODUCT. THE CENTER KEY SLOT WILL BE ON ALL HEADERS REGARDLESS OF SIZE.

4. TWO NON-CRITICAL SIDES OF PIN TIP NOT PLATED, BOTH ENDS.

5. COMPANY LOGO MAY APPEAR IN THIS AREA.

6. CUSTOMER SPECIAL -- "A" SUFFIX INDICATES 0.210/5.33 MATING LENGTH.

7. ADD "HLF" SUFFIX AT THE END OF PART NUMBER FOR LEAD FREE OPTION.

8. PART NUMBERS WITH "H" SUFFIX WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 20 SECONDS IN WAVE SOLDER, INFRA-RED OR VAPOR PHASE SOLDER PROCESS.
PART NUMBERS WITHOUT "H" SUFFIX WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR WAVE SOLDER PROCESS.

9. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATION AS DESCRIBED IN GS-22-008.

10. PLATING OPTIONS:
PERFORMANCE PLATING WILL BE EITHER GOLD OR GXT ON CONTACT OR TAIL, OPTIONAL (78~295u"/2~7.5u) TIN ON TAIL.

11. "THIS PRODUCT HAS 100% TIN PLATING IN THE INTERFACE AND HAS NOT BEEN TESTED FOR WHISKER GROWTH IN ALL INTERCONNECT ENVIRONMENTS."